

OCT 27 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): R. Shane Fazzio
Assignee: Avago Technologies, Ltd.
Title: Microcap Wafer Bonding Apparatus
Serial No.: 10/807,417 Filing Date: March 23, 2004
Examiner: Monica Lewis Group Art Unit: 2822
Docket No.: 10030899-1

San Jose, California
October 27, 2006

Mail Stop RCB
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

This is a response to the August 27, 2006 Final Office Action, which has a statutorily shortened period for response that ends on November 27, 2006. Please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.

-1-

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